



REPETITIVE AVALANCHE RATED AND dv/dt RATED

HEXFET[®] TRANSISTOR

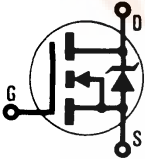
IRFM150

2N7224

JANTX2N7224

JANTXV2N7224

[REF: MIL-S-19500/592]



N-CHANNEL

100 Volt, 0.07 Ohm HEXFET

The HEXFET[®] technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry design achieves very low on-state resistance combined with high transconductance.

The HEXFET transistors also feature all of the well established advantages of MOSFETs such as voltage control, very fast switching, ease of paralleling and temperature stability of the electrical parameters.

They are well suited for applications such as switching power supplies and virtually any application where military and/or high reliability is required.

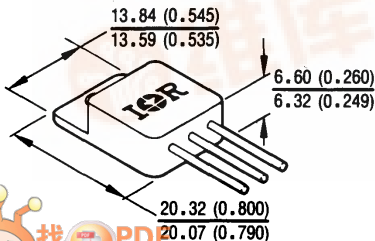
Product Summary

Part Number	BV_{DSS}	$R_{DS(on)}$	I_D
IRFM150	100V	0.07 Ω	34A

FEATURES:

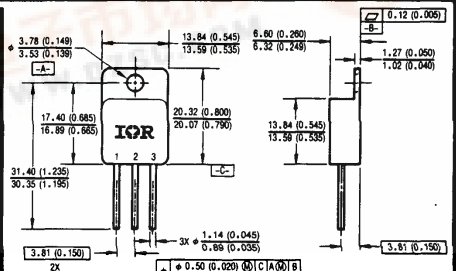
- Repetitive Avalanche Rating
- Isolated and Hermetically Sealed
- Alternative to TO-3 Package
- Simple Drive Requirements
- Ease of Paralleling
- Ceramic Eyelets

CASE STYLE AND DIMENSIONS



CAUTION

BERYLLIA WARNING PER MIL-S-19500



LEGEND

- 1 DRAIN
- 2 SOURCE
- 3 GATE

NOTES:

- 1 DIMENSIONING & TOLERANCING PER ANSI Y14.5M - 1982.
- 2 ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).

Conforms to JEDEC Outline TO-254AA*
Dimensions in Millimeters and (Inches)

*For lead form configurations see pages 1200, 1215, 1216



Absolute Maximum Ratings

Parameter	IRFM150, JANTXV, JANTX-, 2N7224	Units
I_D @ $V_{GS} = 10V$, $T_C = 25^\circ C$	Continuous Drain Current	34
I_D @ $V_{GS} = 10V$, $T_C = 100^\circ C$	Continuous Drain Current	21
I_{DM}	Pulsed Drain Current ①	136
P_D @ $T_C = 25^\circ C$	Max. Power Dissipation	150
	Linear Derating Factor	1.2
		W/K ⑤
V_{GS}	Gate-to-Source Voltage	± 20
E_{AS}	Single Pulse Avalanche Energy ②	150 (See Fig. 12)
I_{AR}	Avalanche Current ①	34 (See E_{AR})
E_{AR}	Repetitive Avalanche Energy ①	15 (See Fig. 13)
dv/dt	Peak Diode Recovery dv/dt ③	5.5 (See Fig. 13)
T_J T_{STG}	Operating Junction Storage Temperature Range	-55 to 150
	Lead Temperature	300 (0.063 in. (1.6 mm) from case for 10s)
	Weight	9.3 (typical)
		g


Electrical Characteristics @ $T_J = 25^\circ C$ (Unless Otherwise Specified)

Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV_{DSS}	100	—	—	V	$V_{GS} = 0V$, $I_D = 1.0$ mA
$\Delta BV_{DSS}/\Delta T_J$	—	0.13	—	V/ $^\circ C$	Reference to $25^\circ C$, $I_D = 1.0$ mA
$R_{DS(on)}$	—	—	0.07	Ω	$V_{GS} = 10V$, $I_D = 21A$ ④
	—	—	0.081		$V_{GS} = 10V$, $I_D = 34A$
$V_{GS(th)}$	2.0	—	4.0	V	$V_{DS} = V_{GS}$, $I_D = 250$ μA
g_{fs}	9.0	—	—	S (0)	$V_{DS} \geq 15V$, $I_{DS} = 21A$ ④
I_{DSS}	—	—	25	μA	$V_{DS} = 0.8 \times$ Max. Rating, $V_{GS} = 0V$
	—	—	250		$V_{DS} = 0.8 \times$ Max. Rating $V_{GS} = 0V$, $T_J = 125^\circ C$
I_{GSS}	—	—	100	nA	$V_{GS} = 20V$
I_{GSS}	—	—	-100		$V_{GS} = -20V$
Q_g	50	—	125	nC	$V_{GS} = 10V$, $I_D = 34A$
Q_{gs}	8	—	22		$V_{DS} = 0.5 \times$ Max. Rating
Q_{gd}	15	—	65		See Fig. 6 and 14
$t_{d(on)}$	—	—	35	ns	$V_{DD} = 50V$, $I_D = 34A$, $R_G = 2.35\Omega$
t_r	—	—	190		
$t_{d(off)}$	—	—	170		See Fig. 11
t_f	—	—	130		
L_D	—	8.7	—	nH	Measured from the drain lead, 6 mm (0.25 in.) from package to center of die.
L_S	—	8.7	—		Measured from the source lead, 6 mm (0.25 in.) from package to source bonding pad.
					Modified MOSFET symbol showing the internal inductances.
C_{iss}	—	3700	—	pF	$V_{GS} = 0V$, $V_{DS} = 25V$
C_{oss}	—	1100	—		$f = 1.0$ MHz
C_{riss}	—	200	—		See Fig. 5
C_{DC}	—	12	—		



IRFM150, JANTXV, JANTX-, 2N7224 Devices

Source-Drain Diode Ratings and Characteristics

Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_S Continuous Source Current (Body Diode)	—	—	34	A	Modified MOSFET symbol showing the integral Reverse p-n junction rectifier. 
I_{SM} Pulsed Source Current (Body Diode) ①	—	—	136		
V_{SD} Diode Forward Voltage	—	—	1.8	V	$T_J = 25^\circ\text{C}$, $I_S = 34\text{A}$, $V_{GS} = 0\text{V}$ ④
t_{rr} Reverse Recovery Time	—	—	500	nS	$T_J = 25^\circ\text{C}$, $I_F = 34\text{A}$, $di/dt \leq 100\text{ A}/\mu\text{s}$ ④
Q_{RR} Reverse Recovery Charge	—	—	2.9	μC	$V_{DD} \leq 50\text{V}$
t_{on} Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $L_S + L_D$.				

Thermal Resistance

Parameter	Min.	Typ.	Max.	Units	Test Conditions
R_{thJC} Junction-to-Case	—	—	0.83	K/W ⑤	Mounting surface flat, smooth, and greased Typical socket mount
R_{thCS} Case-to-Sink	—	0.21	—		
R_{thJA} Junction-to-Ambient	—	—	48		

① Repetitive Rating: Pulse width limited by maximum junction temperature (see figure 9)
Refer to current HEXFET reliability report

③ $I_{SD} \leq 34\text{A}$, $di/dt \leq 70\text{ A}/\mu\text{s}$,
 $V_{DD} \leq BV_{DSS}$, $T_J \leq 150^\circ\text{C}$
Suggested $R_G = 2.35\ \Omega$

⑤ K/W = $^\circ\text{C}/\text{W}$
W/K = $\text{W}/^\circ\text{C}$

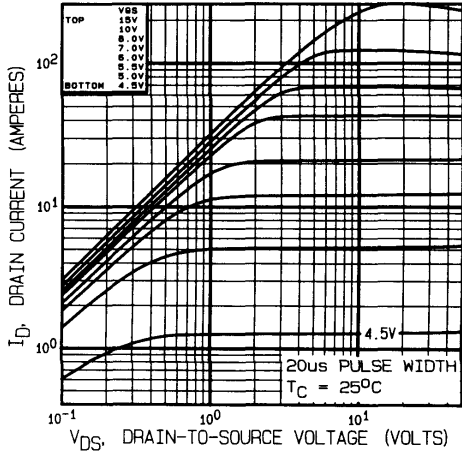


Fig. 1 — Typical Output Characteristics, $T_C = 25^\circ\text{C}$

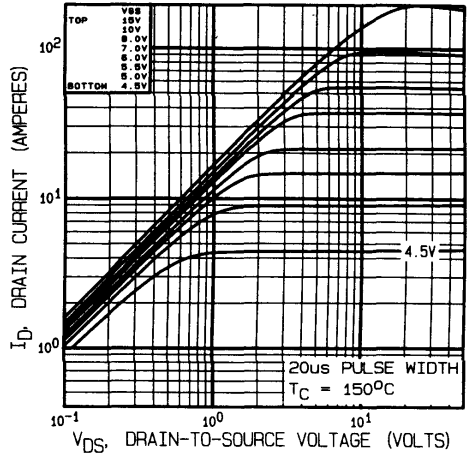


Fig. 2 — Typical Output Characteristics, $T_C = 150^\circ\text{C}$

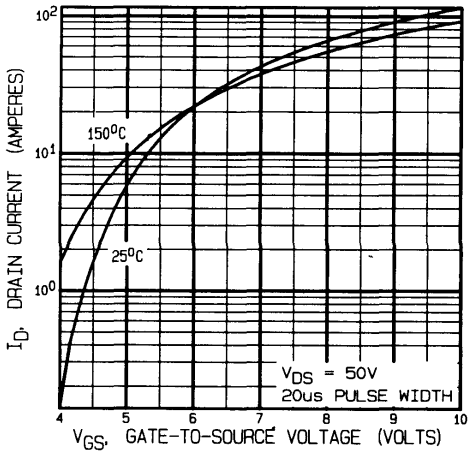


Fig. 3 — Typical Transfer Characteristics

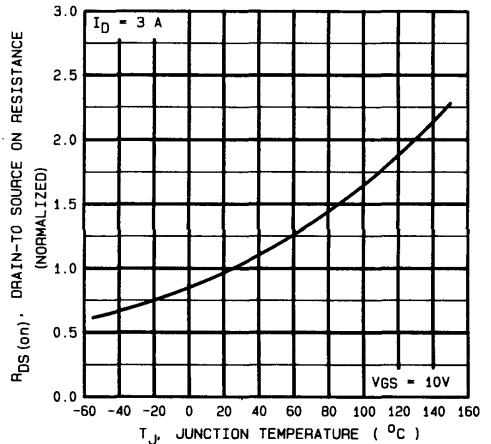


Fig. 4 — Normalized On-Resistance Vs. Temperature



IRFM150, JANTXV, JANTX-, 2N7224 Devices

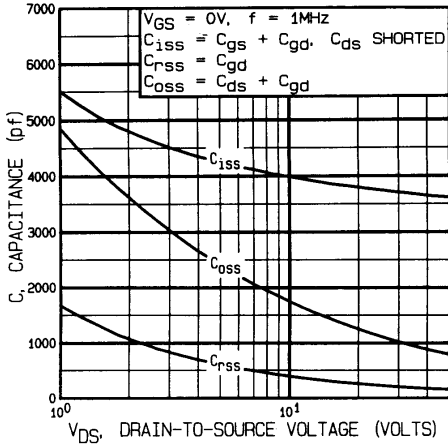


Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage

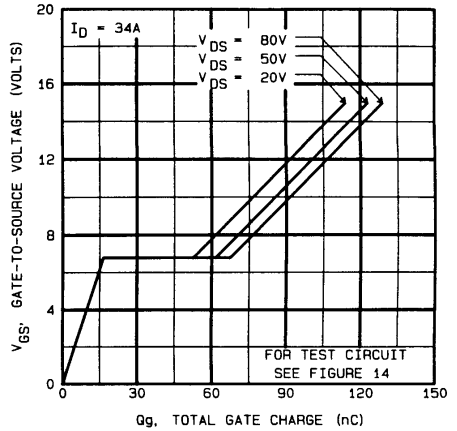


Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage

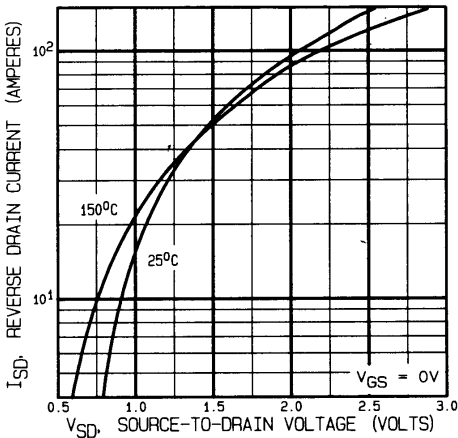


Fig. 7 — Typical Source-Drain Diode Forward Voltage

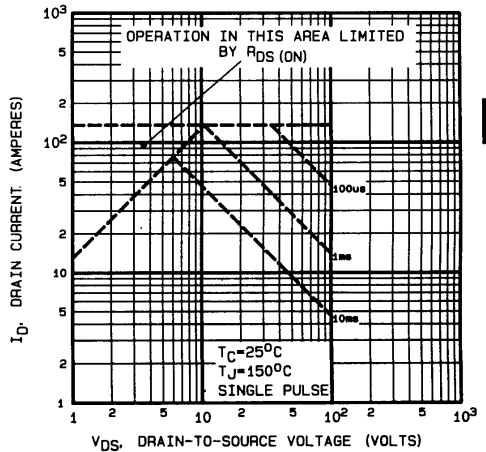


Fig. 8 — Maximum Safe Operating Area

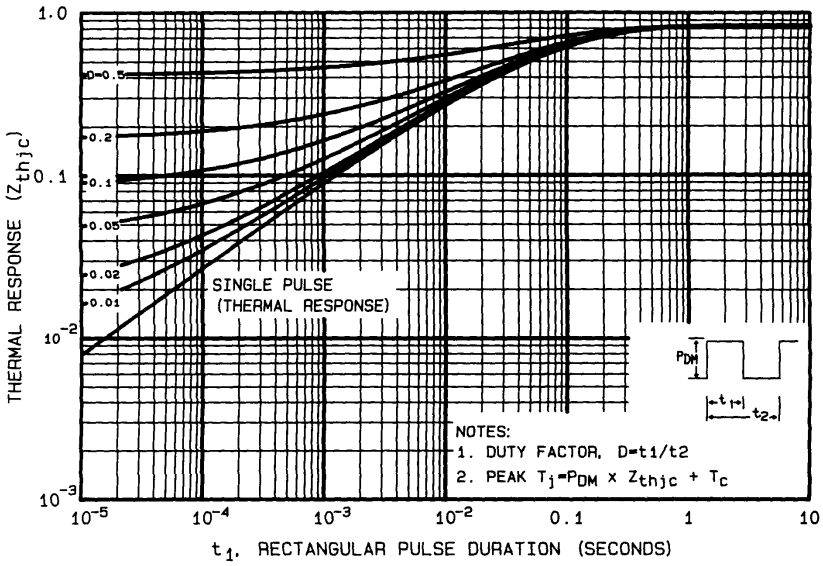


Fig. 9 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

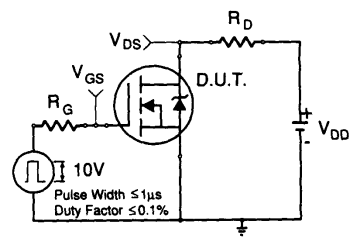
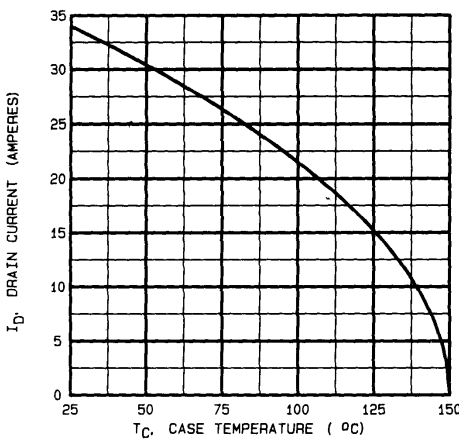
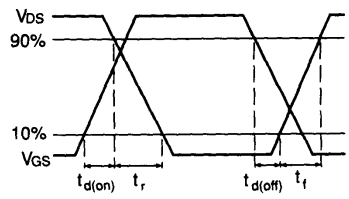


Fig. 11a — Switching Time Test Circuit





IRFM150, JANTXV, JANTX-, 2N7224 Devices

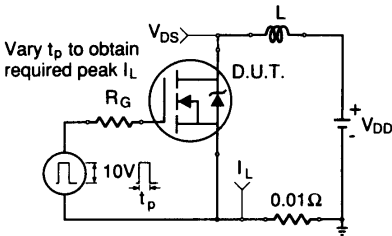


Fig. 12a — Unclamped Inductive Test Circuit

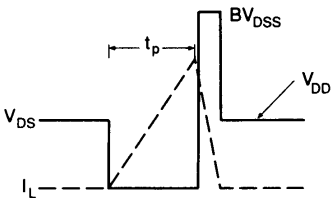


Fig. 12b — Unclamped Inductive Waveforms

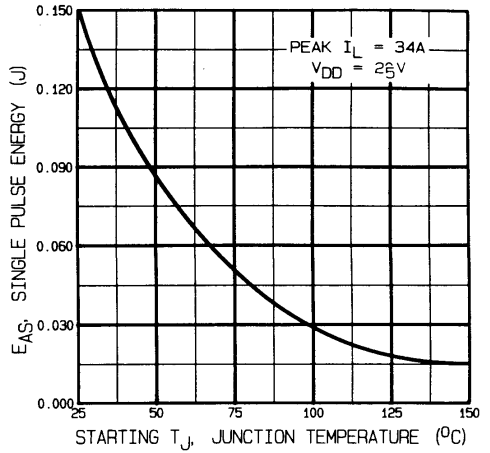


Fig. 12c — Maximum Avalanche Energy Vs. Starting Junction Temperature

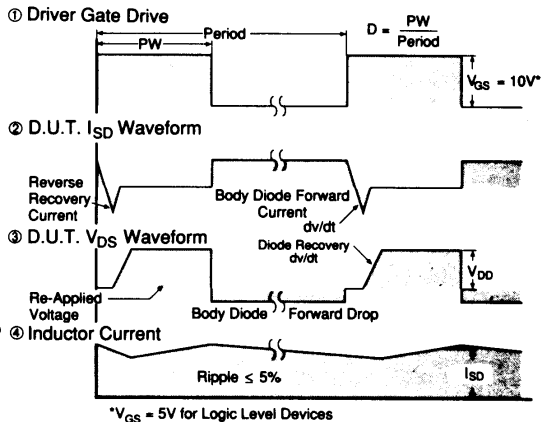
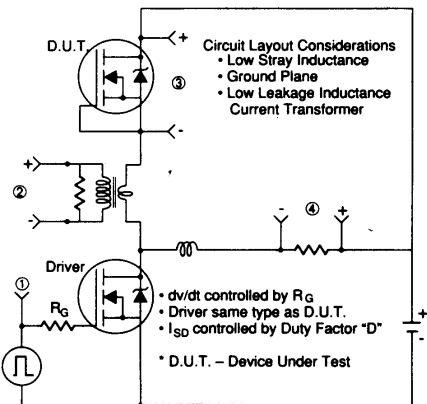


Fig. 13 — Peak Diode Recovery dv/dt Test Circuit

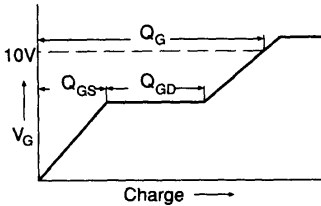


Fig. 14a — Basic Gate Charge Waveform

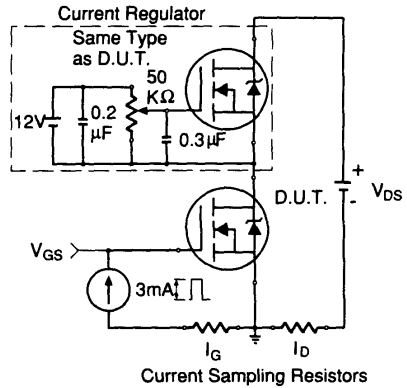


Fig. 14b — Gate Charge Test Circuit

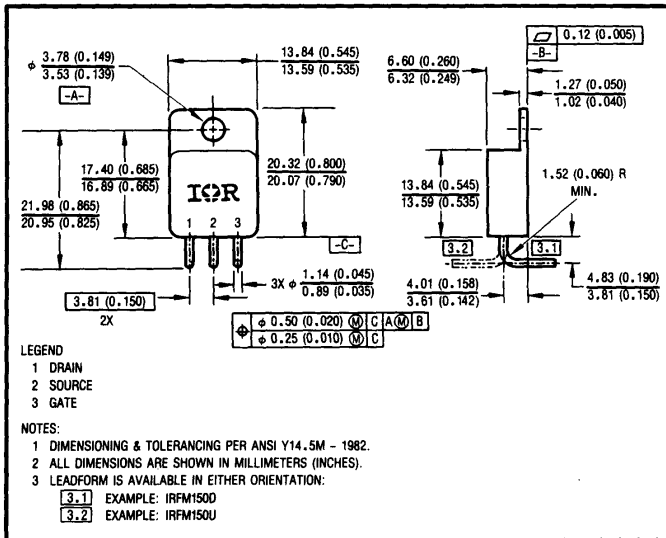


Fig. 15 — Optional Leadforms for Outline TO-254

BERYLLIA WARNING PER MIL-S-19500

Packages containing beryllia shall not be ground, sandblasted, machined, or have other operations performed on them which will produce beryllia or beryllium dust. Furthermore, beryllium oxide packages shall not be placed in acids that will produce fumes containing beryllium.